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This document contains summary information and should be read in conjunction with the 2020-2021 Universal Registration Document, which was filed on July 5, 2021 with the French stock market authority (Autorité des Marchés Financiers, or AMF) under number D.21 0681. The French version of the 2020-2021 Universal Registration Document and an English courtesy translation for information purposes are both available for consultation on the Company’s website (www.soitec.com).

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AGENDA

#01 SOITEC AT A GLANCE

#02 AUTOMOTIVE & INDUSTRIAL

#03 SmartSiC™
SOITEC AT A GLANCE
SOITEC DESIGNS SEMICONDUCTOR MATERIALS TO MAKE THE WORLD

MORE CONNECTED

MORE ENERGY EFFICIENT

MORE INTELLIGENT
FOCUSBING ON 3 STRATEGIC MARKETS TO EXPAND OUR PRODUCT PORTFOLIO

MOBILE COMMUNICATIONS

MAIN DRIVERS
- 5G mmW
- 5G sub-6 GHz
- Mobile infrastructure
- Wi-Fi 6

SOITEC PRODUCTS
- RF-SOI
- FD-SOI
- POI
- GaN

AUTOMOTIVE & INDUSTRIAL

MAIN DRIVERS
- Autonomous cars
- Vehicle electrification
- Infotainment
- Industry 4.0

SOITEC PRODUCTS
- Power-SOI
- FD-SOI
- SiC
- GaN

SMART DEVICES

MAIN DRIVERS
- Edge computing
- 3D sensing & Healthcare
- Smart home & Smart cities
- Data centers

SOITEC PRODUCTS
- FD-SOI
- Imager-SOI
- Photonics-SOI
- PD-SOI
SERVING >7 MILLION WAFERS ADDRESSABLE MARKET* BY FY26

~3M WAFERS

>7M WAFERS

SMART DEVICES
FD-SOI
Imager-SOI
Photonics-SOI
PD-SOI

AUTOMOTIVE & INDUSTRIAL
Power-SOI
FD-SOI
SiC
GaN

MOBILE COMMUNICATIONS
RF-SOI
FD-SOI
POI
GaN

*Engineered substrates market opportunity
FY26 BASE CASE REVENUE MODEL

$668M REVENUE → ~$2B EXPECTED REVENUE

x3 INCREASE REVENUE

x2.5 INCREASE VOLUME

~15% SMART DEVICES

~20% AUTOMOTIVE & INDUSTRIAL

~65% MOBILE COMMUNICATIONS

FY21

FY26

~15% SMART DEVICES

~10% AUTOMOTIVE & INDUSTRIAL

~75% MOBILE COMMUNICATIONS
Our corporate purpose voted in July 2021 perpetuates our engagements towards sustainability and all our stakeholders.
AUTOMOTIVE & INDUSTRIAL
SOITEC PRODUCTS PORTFOLIO
AUTOMOTIVE & INDUSTRIAL

APPLICATIONS
• Autonomous driving systems
• Connected car
• Vehicle electrification
• Industry 4.0

SOITEC PRODUCTS ENABLE
• Autonomous driving
• Infotainment
• Vehicle electrification

Power-SOI
Power management ICs, In-vehicle networking & gate drivers

FD-SOI
MCUs, ADAS-Radars ADAS-Vision

GaN
DC-DC 48V converters

SmartSiC™
Automotive electrification
AUTOMOTIVE MEGATRENDS
DRIVE INNOVATION FROM SYSTEMS TO SUBSTRATES

DIGITALISATION
- Fusion processor
- Radar processor
- Image sensor
- Domain controller

**AUTOMATED VEHICLES**

<table>
<thead>
<tr>
<th>Year</th>
<th>Level 2 &amp; above (%)</th>
<th>ADAS semiconductor content ($)</th>
</tr>
</thead>
<tbody>
<tr>
<td>2020</td>
<td>15%</td>
<td>~200</td>
</tr>
<tr>
<td>2025</td>
<td>35%</td>
<td>~400</td>
</tr>
<tr>
<td>2030</td>
<td>60%</td>
<td>&gt;1400</td>
</tr>
</tbody>
</table>

ELECTRIFICATION
- SiC Diode
- SiC MOSFET
- GaN MOSFET
- PMIC
- BMS
- Gate drivers
- Smart actuator

**CARBON DIOXIDE EMISSIONS**

<table>
<thead>
<tr>
<th>Year</th>
<th>CO₂ emission regulation (gCO₂/km)</th>
<th>Power semiconductor content ($)</th>
</tr>
</thead>
<tbody>
<tr>
<td>2020</td>
<td>120</td>
<td>&lt;100</td>
</tr>
<tr>
<td>2025</td>
<td>95</td>
<td>~200</td>
</tr>
<tr>
<td>2030</td>
<td>59</td>
<td>&gt;400</td>
</tr>
<tr>
<td></td>
<td>further reduction plan in EU</td>
<td>&gt;600</td>
</tr>
</tbody>
</table>

Source: Soitec estimates, Infineon, NXP, IHS, The International Council on Clean Transportation (ICCT) 2020

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ONCE-IN-A CENTURY TRANSFORMATION IN AUTOMOTIVE MARKET

C Connected
- 27M Sales of 5G enabled vehicles in 2026
  - TELEMATIC AND INFOTAINMENT SEMI
  - $15B CAGR 10%

A Autonomous
- 10M Sales of L3 and above vehicles in 2030
  - AUTONOMOUS SEMI
  - $16B CAGR 25%

S Shared
- 40M Global shared fleet in 2030
  - CONSOLIDATED WITH CONNECTED

E Electric
- 45M Global EV sales in 2030 (>50% market share)
  - EV POWER SEMI
  - $8B CAGR 30%

GLOBAL EV SALES (MILLION UNITS)
- 3.2M in 2020
- >20M in 2025
- >45M in 2030

SIC BASED EV POWERTRAIN (%)
- 30% in 2020
- 50% in 2025
- >70% in 2030

(1) v.s. 2020: Zero 5G vehicles; (2) v.s. 2020: Zero L3+ vehicles; (3) v.s. 2020: 19m global shared fleet; (4) v.s. 2020: 3.2m EV sales: 4.2% market share.

SiC IS KEY TO ADDRESS THE CHALLENGES OF EV ADOPTION

- Weight
- Reliability
- Thermal conductivity
- Range anxiety
- Charging time
- Cost

POWERTRAIN – A CRITICAL COMPONENT OF THE EV MARKET
Beyond added value at the system level, SiC will also tackle cost

**POWERTRAIN COST: ~10,000€**

- **Electric motor**
  - Electric motors
  - e-transmission

  ~1,100€

- **Battery pack & modules**
  - Battery pack
  - Modules and cells
  - BMS

  ~8,000€

- **Power electronics**
  - E-drive / inverter (DC/AC)
  - DC/DC Converter
  - On-board charger (AC/DC)

  ~1,500€

**TOTAL SYSTEM COST – 15-20% REDUCTION**

- IGBT Si-based system
- SiC based system

~x2~x3

- Shorter charge time 800V ~50% faster
- Increase battery range ~5%~10% longer
- Reduce system / battery costs ~$500~$1,000

Source: AlixPartners, Bernstein, Infineon, Soitec estimates
SmartSiC™ is a new generation substrate with ultra low resistivity and better usage of monoSiC, benefitting from the re-usability.

**PolySiC base wafer:**
- Ultra low resistivity
- Enhanced geometry

**Conductive bonding (metal free)**

**Thick C-face donor monoSiC (SmartSiC™-Performance)**
- or by epitaxy (SmartSiC™-Advanced)
- & Refresh multiple times

**Ultra high conductivity SiC**

**Vertical conductivity & Geometry**

**Reducing Capex & Opex for device manufacturers**

**~20,000t of CO₂**

Energy savings per 500k wafers vs. current SiC technologies
SMART CUT™ PROCESS ADAPTED TO SiC
FULL R&D PILOT LINE RUNNING, ISO 9001 CERTIFICATION GRANTED

**Donor wafer**
(Prime monocrystalline SiC)

- 1. Starting SiC
- 2. Surface prep
- 4. Conductive Bonding
- 6. Finishing steps
- 7. Donor wafer becomes new wafer SiC

**Handle wafer**
(Ultra high conductivity polycrystalline SiC)

- 3. Implantation
- 5. Splitting

SiC Receiver

SmartSiC™

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PolySiC FOR SmartSiC™

STRATEGIC PARTNERSHIPS TO STRENGTHEN OUR VALUE PROPOSITION

**STRATEGIC PARTNERSHIP**

**Scope**
- Strategic JDA to develop a *new range of polySiC substrates* for the EV market
- Soitec and Mersen teams will leverage Soitec’s Substrate Innovation Center within CEA-Leti to validate progress towards industrialization

**Strategic Rationale**
- *Very low electric resistivity* polySiC substrates, in conjunction with SmartCut™ technology, will optimize Power / SiC Power components
- *polySiC compatible* with SmartCut™ technology and customers specs
- polySiC substrates will enable *higher energy efficiency*, fostering the development of more energy efficient Electric Vehicles

<table>
<thead>
<tr>
<th>Cost of ownership</th>
<th>Traditional SiC Monocrystalline</th>
<th>SmartSiC™ Polycrystalline</th>
</tr>
</thead>
<tbody>
<tr>
<td>Electrical performance</td>
<td>Limited by technology</td>
<td>High, enabling ultra high conductivity</td>
</tr>
</tbody>
</table>

**BOLT ON ACQUISITION**

**NOVASiC**

State of the art wafering and polishing services for high-performance semiconductors and industrial crystals

**Strategic Rationale**
- Unique expertise to bring *critical technology acceleration* for SmartSiC™ and internalize polishing capabilities
- Leverage *specific know-how* to integrate into global SmartSiC™ differentiation
- Leverage *customer access* with leading SiC bulk & device makers
- Opportunity to accelerate *cost of ownership reduction roadmap*

**NOVASiC Business & Operations**
- Polishing Services – key product: 150mm SiC epitaxy reclaim
- Epitaxy, Wafer dicing, Edge grinding, Laser marking, Wire sawing

**High precision Polishing**
- Improved RE-USABILITY

**Flatness through surface preparation**
- Lower DIE SIZE

**High final surface quality**
- Higher YIELD
SMARTSiC™ ENGINEERED SUBSTRATES IN 150 & 200mm 
SAMPLING AND PROTOTYPING PHASE BEFORE QUALIFYING

FROM SiC BULK

TO SMARTSiC™ ENGINEERED SUBSTRATE

TO POWER ELECTRONICS DEVICES 
(DIODES AND MOSFET)
SMARTSiC™ DELIVERS SUPERIOR DEVICE PERFORMANCE

Proven higher amps through diodes

Enabling new designs for die optimization

Proven long-term reliability through vertical Schottky structure

Power cycling test validated after >300,000 cycles

Spec limit: +20% drift
SMARTSiC™ ROADMAP

VALUE PROPOSITION

SmartSiC™ vs SiC: Greener, Faster and Better
• 20,000 Tons of CO2 reduction for each 500,000 wafers vs. SiC
• 200mm scalability to accelerate SiC adoption through 10x re-usability
• Enabling new generation of SiC devices thanks to >7% improvement of resistivity

EXISTING AND FUTURE APPLICATIONS
• Traction inverter system (EV's, Railways)
• On-board chargers (EV's)
• DC/DC converter (EV's, Renewables)
• DC/AC Inverters (Renewables, Industry)
• Advanced usage of SiC: Integrated motor drives, solid state breakers...

FAMILY “SMARTSiC™ PRODUCT” ROADMAP FROM FY23

Mid-FY24

- Ultra low defectivity SmartSiC™
- 200mm Low resistivity SmartSiC™
- 150mm Low resistivity SmartSiC™

Timeline

First production
EXPANDING OUR MANUFACTURING FOOTPRINT IN BERNIN TO PRODUCE HIGH VOLUME SMARTSiC™ SUBSTRATES

150 & 200mm diameters to be produced in the Fab

March 31st, 2022
Kick-off construction of Bernin 4 for SmartSiC™

High single digit % of Soitec FY26 revenue generated by SmartSiC™

Up to 1 million SmartSiC™ wafers per year (Bernin 4 fab potential capacity)

Up to 400 direct new jobs expected to be created

H2 FY24
Plant Qualification

Q3 FY24
First revenue

FY25
Ramp up

FY26
High single digit % of FY26 $2bn expected revenue

High single digit % of FY26 expected revenue
THANK YOU